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(54) LIQUID COOLED PLATE AND ELECTRONIC COMPUTING DEVICE

(71) Applicant: SHENZHEN ENVICOOL TECHNOLOGY CO., LTD., Shenzhen

(CN)

(72) Inventors: Xi YANG, Shenzhen (CN); Zhao LU,

Shenzhen (CN); Kailun ZHANG, Shenzhen (CN); Weiyang LAI, Shenzhen (CN); Lichuan WEI, Shenzhen (CN); Zhiqiang CAI,

Shenzhen (CN)

(73) Assignee: SHENZHEN ENVICOOL

TECHNOLOGY CO., LTD., Shenzhen

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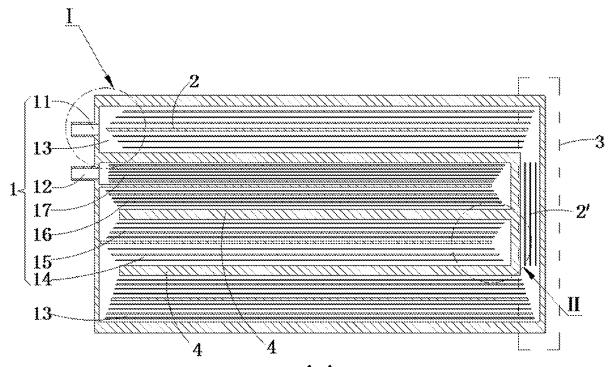
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(57)**ABSTRACT**

A liquid cooled plate and an electronic computing device are provided. The liquid cooled plate includes multiple channels communicated in sequence, and adjacent channels are communicated via a communicating portion. Multiple partitions divide each of the channels to multiple flow passages, and a part of each of the partitions extends into the communicating portion, and lengths of the multiple partitions extending into the communicating portion gradually increases or decreases according to a preset rule. With this arrangement, the coolant can be collected and redistributed before entering the next channel, which is more conducive to the uniform distribution of the coolant, thereby improving the overall heat exchange capacity of the liquid cooled plate, and thus can better meet the actual usage requirements.



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